

Title of Change:	Qualification of High Frequency Voltage Regulation (HFVR) Gen1.0 Process in ON Semiconductor wafer fabrication facility in Niigata, Japan.		
Proposed first ship date:	29 December 2016		
Contact information:	Contact your local ON Semiconductor Sales Office or <Joe.Chong@onsemi.com>		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <tomas.vajter@onsemi.com>.		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	Affected first lot will be identified the date code (WW41)		
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____		
Change Sub-Category(s): <div> <input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____ </div>			
Sites Affected: <div> <input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Niigata, Japan <input type="checkbox"/> External Foundry/Subcon site(s) </div>			
Description and Purpose: The purpose of this Final PCN is to notify customers of adding a new wafer fab location/ site for HFVR (High Frequency Voltage Regulation) Gen1.0 process/products. The High Side FET of the affected part numbers is currently manufactured from Oudenaarde, Belgium. After the expiration of the Final PCN, ON Semiconductor will produce the affected part number from Oudenaarde, Belgium and/or Niigata, Japan Wafer FAB Facilities.			

**Reliability Data Summary:**

QV DEVICE NAME : NCP3231AMNTXG

PACKAGE: QFN 40 6*6

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	TA=150C, VDSS=22V	1008 hrs	0/84
HTGB	JESD22-A108	TA=150C, Bias = 8V	1008 hrs	0/84
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=25 C, Delta Tj = 100C max	15000 cyc	0/84
TC	JESD22-A104	Ta= -55°C to +150°C	500 cyc	0/84
H3TRB	JESD22-A101	TA = 85°C/85% RH	1008 hrs	0/84
HAST	JESD22-A110	130°C/85% RH	96 hrs	0/84
uHAST	JESD22-A118	130°C/85% RH	96 hrs	0/84

Electrical Characteristic Summary:

Electrical characteristics are not impacted.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
NCP3231AMNTXG	NCP3231AMNTXG
NCP3231MNTXG	NCP3231AMNTXG
NCP5339MNTXG	NCP3231AMNTXG